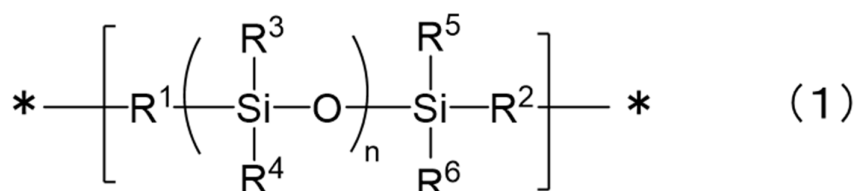


ADHESIVE, SUBSTRATE HAVING ADHESIVE, CIRCUIT BOARD HAVING ADHESIVE LAYER, LAYERED PRODUCT, METHOD FOR PRODUCING LAYERED PRODUCT, AND METHOD FOR PRODUCING SEMICONDUCTOR DEVICE

ABSTRACT

The present invention aims to provide a pressure sensitive adhesive having high pressure sensitive adhesiveness and heat resistance and serves to makes it possible to transfer and mount a large number of semiconductor elements at once even when the process involves a step for applying heat to the semiconductor elements. It provides a pressure sensitive adhesive including a polyimide copolymer (A) having at least an acid dianhydride residue and a diamine residue and also comprising a dimer acid epoxy resin (B), wherein the diamine residue has a diamine residue (A1) as represented by the formula (1) in which n is a natural number of 1 or more and 15 or less (hereinafter referred to as the diamine residue (A1)), a diamine residue (A2) as represented by the formula (1) in which n is a natural number of 16 or more and 50 or less (hereinafter referred to as the diamine residue (A2)), and a diamine residue (A3) having a phenolic hydroxyl group (hereinafter referred to as the diamine residue (A3)) and also wherein the diamine residue (A1) accounts for 50.0 mol% or more and 95.0 mol% or less, the diamine residue (A2) accounting for 1.0 mol% or more and 40.0 mol% or less, and the diamine residue (A3) accounting for 1.0 mol% or more and 30.0 mol% or less, of all diamine residues, which account for 100.0 mol%, in the polyimide copolymer (A).



[No Figure]